

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Michael S. Leung, et al.

Serial No. : 10/666,399

Filed : September 18, 2003

Examiner : Kalam, Abul

Art Unit : 2814

Customer No. : 23935

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

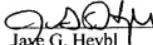
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

NOTIFICATION OF FILING OF DIVISIONAL APPLICATION

Notification is hereby being made of the filing of a divisional application for the above application.

Respectfully submitted,

Dated: 7/10/10



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